Package Outline Drawing
W5x7.35
35 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)
Rev 0, 11/14

NOTES:
2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. All dimensions are in millimeters.
6. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.

Plastic Packages for Integrated Circuits